

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#2/a  
8/18/00  
Sunder

In re Patent Application of:  
**ZENG**

Serial No. **Not yet assigned**

Filing Date: **Herewith**

For: **SEMICONDUCTOR DEVICE HAVING  
REDUCED EFFECTIVE SUBSTRATE  
RESISTIVITY AND ASSOCIATED  
METHODS**

) Examiner: A. Wilson

)

) Art Unit: 2815

)

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Assistant Commissioner for Patents  
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Sir:

Prior to the calculation of fees and examination of  
the present application, please enter the amendments and  
remarks set out below.

In the Claims:

Please cancel Claims 1-51

Please add new Claims 52-75.

52. A method for making a semiconductor device  
comprising a semiconductor substrate having a lowered  
effective electrical resistivity, the method comprising:  
forming at least one device active region in the  
semiconductor substrate adjacent a first surface thereof;

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